

GOVERNMENT OF INDIA
MINISTRY OF ELECTRONICS AND INFORMATION TECHNOLOGY
LOK SABHA
UNSTARRED QUESTION NO. 4064
TO BE ANSWERED ON: 12.08.2026

**CREATION OF JOBS UNDER SEMI-CONDUCTOR MISSION IN
ODISHA**

†4064. DR. SAMBIT PATRA:

Will the Minister of ELECTRONICS AND INFORMATION TECHNOLOGY be pleased to state:

- (a) the total number of direct and indirect jobs targeted to be created under the Semi-conductor Mission in Odisha;
- (b) whether the Government is implementing any scheme to establish semi-conductor skill development centres to train the youth of the State in chip manufacturing and designing and if so, the details thereof;
- (c) whether the Government proposes to provide financial and technical assistance to local ITIs and polytechnics in Odisha to prepare them for the semi-conductor ecosystem; and
- (d) if so, the details of the number of semiconductor fabrication and design units, committed investments and timelines under the Central scheme approved for the Semi-conductor Mission in Odisha?

ANSWER

MINISTER OF STATE FOR ELECTRONICS AND INFORMATION TECHNOLOGY
(SHRI JITIN PRASADA)

(a) to (d): Recognising the importance of semiconductors, the Government launched Semicon India Programme in January 2022 for setting up of semiconductor fabs, display fabs semiconductor packaging and also for promotion of Indian designed chips. Under this Programme, Government has approved 12 manufacturing projects with total investment commitments of about ₹1.64 lakh crore.

Out of these 12 projects, following two projects have been approved in the state of Odisha:

- (i) 3D Glass Solutions Inc. (3DGS) is setting up of a vertically integrated advanced packaging and embedded glass substrate manufacturing. The proposed installed capacity for glass panel substrate production, assembly and 3D Heterogeneous Integration (3DHI) is around 5800 panels/ month, 4.20 million units/ month, and 1100 units/ months respectively. This project has the potential to generate more than 280 direct employment opportunities and many indirect employment opportunities in the ancillary units.
- (ii) SicSem Private Limited is setting up Silicon Carbide (SiC) based Compound Semiconductors fab and Assembly, Testing, Marking, and Packaging (ATMP) facility with fabrication capacity of 5,000 wafers/month and packaging capacity of 8 million units/month.

The project has the potential to generate around 1000 direct employment opportunities along with many indirect jobs.

Further, as the semiconductor industry is a foundational industry, these units have a cascading effect on employment generation in the other sectors and the supply chain down the line.

For supporting design of semiconductor chips, availability of Electronic Design Automation (EDA) tools is an essential requirement. These EDA tools are very costly creating high entry barriers for the new companies in the area of semiconductor design. Therefore, the Government has enabled free of cost access to EDA tools under the Design Linked Incentive (DLI) Scheme of Semicon India Programme. One startup has been approved in Odisha to avail free of cost access to the EDA tools.

The government also launched Chips to Startup (C2S) programme to provide industry ready manpower in chip design. Under this programme, access to cutting-edge EDA tools has been provided at no cost. The list of institutions supported under C2S programme in the state of Odisha are as follows:

#	District	Institute
1	Ganjam	Parala Maharaja Engineering College, Berhampur
2	Sundargarh	National Institute of Technology Rourkela
3	Khordha	Indian Institute of Technology Bhubaneswar
		International Institute of Information Technology Bhubaneswar
		Kalinga Institute of Industrial Technology (KIIT), Bhubaneswar, Odisha
		Trident Academy of Technology, Bhubaneswar
		Centurion University of Technology and Management, Odisha
		Siksha 'O' Anusandhan, Bhubaneswar, Odisha
		C. V. Raman Global University, Odisha
		Biju Patnaik University of Technology (BPUT), Rourkela, Odisha
		Silicon University, Odisha
4	Sambalpur	Veer Surendra Sai University of Technology, Sambalpur, Odisha
5	Rayagada	Gandhi Institute of Engineering and Technology (GIET) University, Gunupur, Odisha

NIELIT, an autonomous society of the Government, is also actively contributing to strengthening India's Electronics System Design and Manufacturing (ESDM) and semiconductor ecosystem through advanced skilling, capacity building, indigenous R&D, infrastructure development and digital platforms. In the State of Odisha, NIELIT Bhubaneswar, along with its extension centre at NIELIT Baleswar, is undertaking education, skilling and capacity-building initiatives in Electronics and Information Technology (E&IT), including semiconductor and chip design technologies.

Further, the Government of India launched Pradhan Mantri Skilling and Employability Transformation through Upgraded ITIs (PM-SETU) scheme with a total outlay of Rs. 60,000 crore, to enhance the overall quality and relevance of vocational training in the country. The PM-SETU scheme envisages to upgrade 1,000 Government ITIs in hub and spoke arrangement with the help of Anchor Industry Partners (AIPs).

The upgrade includes smart classrooms, modern labs, digital content, and new courses aligned to industry needs. The Scheme also targets the capacity Augmentation of five National Skill Training Institutes (NSTIs) located in Bhubaneswar, Chennai, Hyderabad, Kanpur, and Ludhiana, including setting-up sector-specific National Centres of Excellence for skilling, with focus on advanced training of trainers with global partnership, and curriculum development. The selection of ITIs under the PM-SETU scheme is led by the respective State/ Union Territory (UT) Governments in consultation with industry, ensuring alignment with emerging skill needs and local industrial potential.
